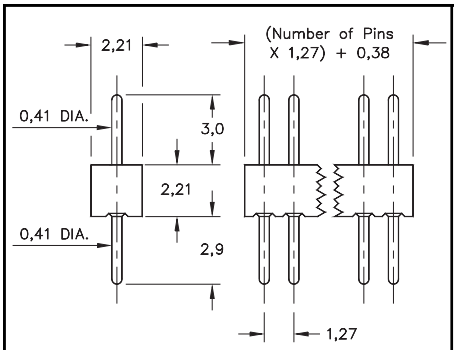


Fig. 1

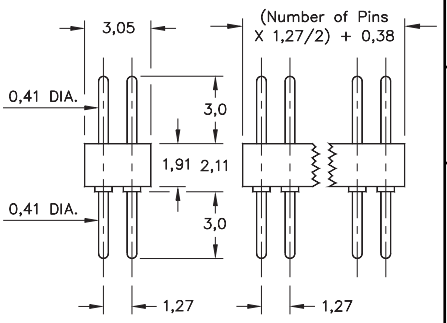


Fig. 2

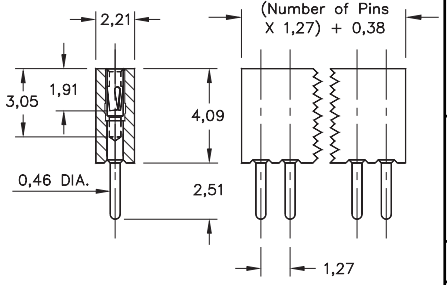


Fig. 3

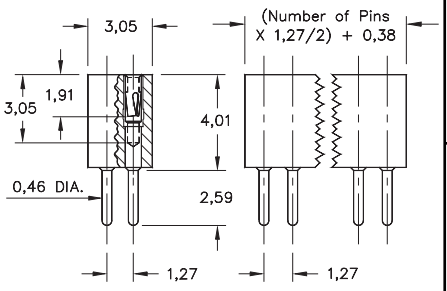


Fig. 4

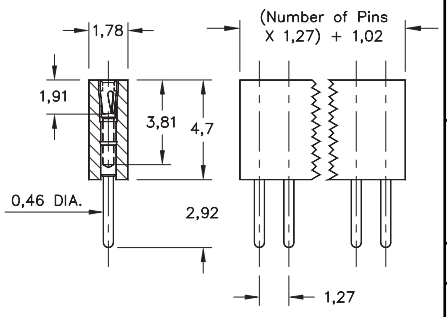
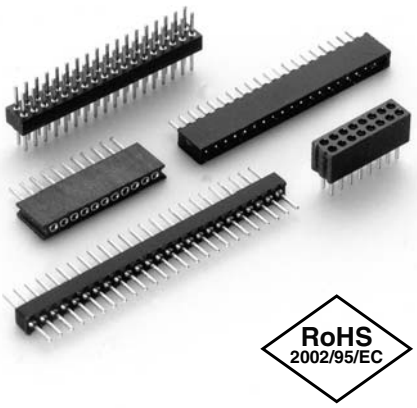


Fig. 5

- Series 850 single and double row interconnects have 1,27 pin spacing & permit board stacking as low as 6,3.
- Pin headers have 0,41 dia. pins (MM #4006-0). See page 175 for details.
- MM #0467 and MM #4890 receptacles use Hi-Rel, 3-finger BeCu #11 contacts rated at 3 amps. (#11 contact accepts pin diameters from 0,38 - 0,51). See pages 129 and 131 for details.
- Insulators are high temp. thermoplastic, suitable for all soldering operations.



Ordering Information

Fig. 1 — **Single Row** — **2,21 Profile Pin Header**

850-XX-0_ _-10-001000

Specify # of pins → 01-50

Fig. 2 — **Double Row** — **1,91 Profile Pin Header**

852-XX-_ _ _-10-001000

Specify # of pins → 002-100

For Electrical, Mechanical & Enviromental Data, See pg. 4

XX=Plating Code See Below

For RoHS compliance select ◇ plating code.

SPECIFY PLATING CODE XX=	10◇	90	40◇	
Pin Plating	0,25µm Au	5,08µm Sn/Pb	5,08µm Sn	

Fig. 3 — **Single Row** — **4,09 Profile Socket**

851-XX-0_ _-10-001000

Specify # of pins → 01-50

Fig. 4 — **Double Row** — **4,09 Profile Socket**

853-XX-_ _ _-10-001000

Specify # of pins → 002-100

Fig. 5 — **Single Row** — **4,7 Profile Socket**

851-XX-0_ _-10-002000

Specify # of pins → 01-77

For Electrical, Mechanical & Enviromental Data, See pg. 4

XX=Plating Code See Below

For RoHS compliance select ◇ plating code.

SPECIFY PLATING CODE XX=			93	99		43◇	
Sleeve (Pin)			5,08µm Sn/Pb	5,08µm Sn/Pb		5,08µm Sn	
Contact (Clip)			0,76µm Au	5,08µm Sn/Pb		0,76µm Au	